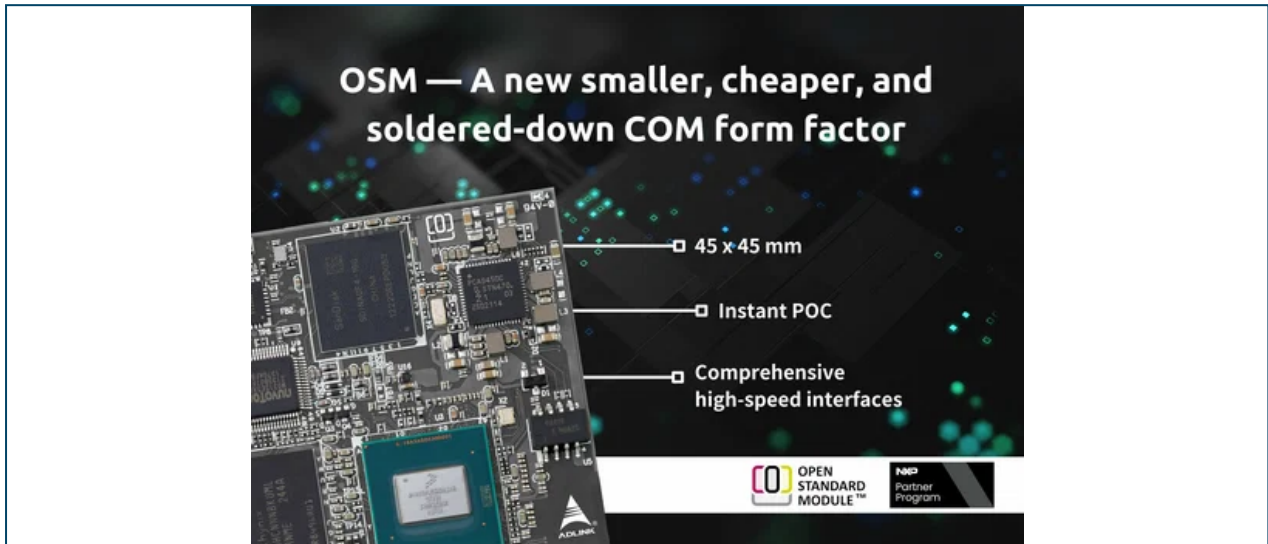


ADLINK DEBUTING ITS OSM PRODUCT LINE OF EMBEDDED MODULES



In a versatile standard for small-size and low-cost soldered-down including the OSM-IMX93 (NXP i.MX 93), OSM-IMX8MP (NXP i.MX 8M Plus) a complete and competitive product portfolio based on leading edge CPU cores suited for a variety of applications will be announced and available shortly(Q2'24).

The first available member- OSM-IMX93- is an OSM R1.1 Size-L module featuring NXP® i.MX93 series processor with 2-core Arm Cortex-A55 & M33. With its in-SoC Arm Ethos U-65 microNPU, the module is made for edge solutions needing on-device AI processing at ultra-low power.

The OSM-IMX93 module supports LVDS and DSI graphics output, 2x GbE (1 TSN capable), 2x CAN bus, I2S audio codec interface, USB2 interfaces, and provides 15-year product availability.

Boasting the highest safety standards with a separate security island and available with rugged operating temperature options (-40°C to 85°C), the OSM-IMX93 is your ideal solution for various edge AI applications.



For full product
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Adlink's mission is to affect positive change in society and industry by connecting people, places and assets with artificial intelligence; we do this through the delivery of leading edge, robust and reliable hardware and software solutions that d

